



FINAL PRODUCT/PROCESS CHANGE NOTIFICATIONGeneric Copy

28-Mar-2007**SUBJECT: ON Semiconductor Final Product/Process Change Notification #16002****TITLE: Final Notification for SO8-MCM Expansion to OSPI****PROPOSED FIRST SHIP DATE: 28-May-2007****AFFECTED CHANGE CATEGORY(S): Assembly and Test****AFFECTED PRODUCT DIVISION(S): DCG, Digital and Consumer Group; Applications Specific Integrated Products Division.****FOR ANY QUESTIONS CONCERNING THIS NOTIFICATION:**Contact your local ON Semiconductor Sales Office or Paul Alonas <paul.alonas@onsemi.com>**SAMPLES:** Contact your local ON Semiconductor Sales Office**ADDITIONAL RELIABILITY DATA:** AvailableContact your local ON Semiconductor Sales Office or Rick Luevanos <r.luevanos@onsemi.com>**NOTIFICATION TYPE:** Final Product/Process Change Notification (FPCN)

ON Semiconductor will consider this change approved unless specific conditions of acceptance are provided in writing within 30 days of receipt of this notice. To do so, contact your local ON Semiconductor Sales Office.

DESCRIPTION AND PURPOSE:

This is the Final Process Change Notice to IPCN 15506 located at www.onsemi.com to notify customers of the capacity expansion of the ON Semiconductor assembly/test location at Carmona, Philippines (OSPI) for 8 lead narrow SOIC MCM (SO-8 Multi Chip Module) packages. The devices listed on this FPCN have historically been assembled or tested at the ASE assembly/test facility located in Chung Li, Taiwan. At the expiration of this Final PCN, these devices may be processed at either location. The ON Semiconductor facility at Carmona, Philippines is fully qualified and has been producing the SOIC narrow body Product for many years.


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RELIABILITY DATA SUMMARY:
Table 1. Reliability Evaluation Results for Device LC03-6R2
Qualification Points in BOLD

#	Test	Name	Test Conditions	End Point Req's	Test Results	(rej/ss)	(rej/ss)	(rej/ss)
					Read Point	Lot A	Lot B	Lot C
1	Prep	Sample preparation and initial part testing	various	---	Initial Electrical	done	done	done
2	HTSL	High Temp Storage Life	150°C for 1008 hours	c = 0, Room	504 Hrs	0/77	0/77	0/77
3	PC	MSL1 Preconditioning	3 IR @ 260 deg C	c = 0, Room				
4	TC-PC	Precond. Temp Cycle	-65/+150 C	c = 0, Room	500 cyc	0/77	0/77	0/77
5	HAST-PC	Precond. HAST	TA= +130C, RH = 85%, PSIG= 18.8, bias	c = 0, Room	96 hrs	0/80	0/80	0/80
6	AC-PC	Precond. Autoclave	TA = 121 C, RH = 100%,PSIG = 15	c = 0, Room	96 hrs	0/77	0/77	0/77

Table 2. Reliability Evaluation Results for Device NUP4201DR2
Qualification Points in BOLD

#	Test	Name	Test Conditions	End Point Req's	Test Results	(rej/ss)	(rej/ss)	(rej/ss)
					Read Point	Lot A	Lot B	Lot C
1	Prep	Sample preparation and initial part testing	various	---	Initial Electrical	done	done	done
2	HTSL	High Temp Storage Life	150°C for 1008 hours	c = 0, Room	504 Hrs	0/80	0/80	0/80
					1008 Hrs	0/80	0/80	0/80
3	PC	MSL1 Preconditioning	3 IR @ 260 deg C	c = 0, Room				
4	TC-PC	Precond. Temp Cycle	-65/+150 C	c = 0, Room	500 cyc	0/80	0/80	0/80
5	HAST-PC	Precond. HAST	TA= +130C, RH = 85%, PSIG= 18.8, bias	c = 0, Room	96 hrs	0/80	0/80	0/80
6	AC-PC	Precond. Autoclave	TA = 121 C, RH = 100%,PSIG = 15	c = 0, Room	96 hrs	0/80	0/80	0/80

ELECTRICAL CHARACTERISTIC SUMMARY:

Because no die changes were associated with this FPCN the device characteristics have not changed from the Data Sheets already published. You may obtain data sheets from your local sales representative.

CHANGED PART IDENTIFICATION:

Devices assembled at ASECL, Taiwan will contain an "X" in the first digit of the second line of marking.

Devices assembled at ON Semiconductor, Carmona, Philippines will contain a "P" as the first digit of the second line of marking.



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AFFECTED DEVICE LIST

NUP4201DR2
LC03-6R2
SRDA05-4R2